



H11AA1M, H11AA2M, H11AA3M, H11AA4M AC Input/Phototransistor Optocouplers

Features

- Bi-polar emitter input
- Built-in reverse polarity input protection
- Underwriters Laboratory (UL) recognized File #E90700, Volume 2
- VDE approved File #102497 (ordering option 'V')

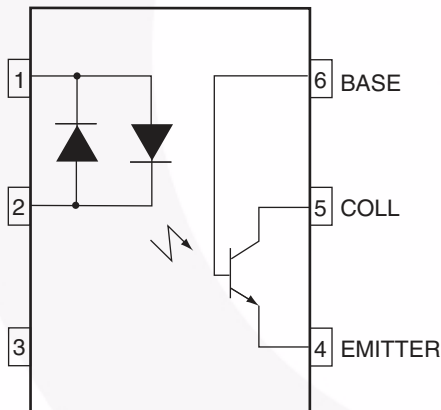
Applications

- AC line monitor
- Unknown polarity DC sensor
- Telephone line interface

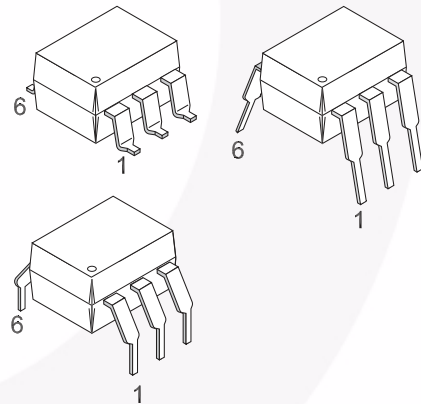
Description

The H11AAXM series consists of two gallium-arsenide infrared emitting diodes connected in inverse parallel driving a single silicon phototransistor output.

Schematic



Package Outlines



H11AA1M, H11AA2M, H11AA3M, H11AA4M — AC Input/Phototransistor Optocouplers

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Device | Value | Units |
|---------------------|---|--------|----------------|----------------------|
| TOTAL DEVICE | | | | |
| T_{STG} | Storage Temperature | All | -40 to +150 | $^\circ\text{C}$ |
| T_{OPR} | Operating Temperature | All | -40 to +100 | $^\circ\text{C}$ |
| T_{SOL} | Lead Solder Temperature | All | 260 for 10 sec | $^\circ\text{C}$ |
| P_D | Total Device Power Dissipation Derate Linearly From 25°C | All | 250 | mW |
| | | | 2.94 | mW/ $^\circ\text{C}$ |
| EMITTER | | | | |
| I_F | Continuous Forward Current | All | 60 | mA |
| $I_F(\text{pk})$ | Forward Current – Peak (1 μs pulse, 300 pps) | All | ± 1.0 | A |
| P_D | LED Power Dissipation Derate Linearly From 25°C | All | 120 | mW |
| | | | 1.41 | mW/ $^\circ\text{C}$ |
| DETECTOR | | | | |
| I_C | Continuous Collector Current | All | 50 | mA |
| P_D | Detector Power Dissipation Derate linearity from 25°C | All | 150 | mW |
| | | | 1.76 | mW/ $^\circ\text{C}$ |

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

Individual Component Characteristics

| Symbol | Parameter | Test Conditions | Device | Min. | Typ.* | Max. | Unit |
|-----------------|---|--------------------------------------|-------------------------------|------|-------|------|------|
| EMITTER | | | | | | | |
| V_F | Input Forward Voltage | $I_F = \pm 10\text{mA}$ | All | | 1.17 | 1.5 | V |
| C_J | Capacitance | $V_F = 0\text{V}, f = 1.0\text{MHz}$ | All | | 80 | | pF |
| DETECTOR | | | | | | | |
| BV_{CEO} | Breakdown Voltage Collector to Emitter | $I_C = 1.0\text{mA}, I_F = 0$ | All | 30 | 100 | | V |
| BV_{CBO} | Collector to Base | $I_C = 100\mu\text{A}, I_F = 0$ | All | 70 | 120 | | V |
| BV_{EBO} | Emitter to Base | $I_E = 100\mu\text{A}, I_F = 0$ | All | 5 | 10 | | V |
| BV_{ECO} | Emitter to Collector | $I_E = 100\mu\text{A}, I_F = 0$ | All | 7 | 10 | | V |
| I_{CEO} | Leakage Current Collector to Emitter | $V_{CE} = 10\text{V}, I_F = 0$ | H11AA1M H11AA3M H11AA4M | | 1 | 50 | nA |
| | | | H11AA2M | | 1 | 200 | |
| C_{CE} | Capacitance Collector to Emitter | $V_{CE} = 0, f = 1\text{MHz}$ | All | | 10 | | pF |
| C_{CB} | Collector to Base | $V_{CB} = 0, f = 1\text{MHz}$ | All | | 80 | | pF |
| C_{EB} | Emitter to Base | $V_{EB} = 0, f = 1\text{MHz}$ | All | | 15 | | pF |

*Typical values at $T_A = 25^\circ\text{C}$

Transfer Characteristics

| Symbol | Characteristics | Test Conditions | Device | Min. | Typ.* | Max. | Units |
|---------------|---|---|---------|------|-------|------|-------|
| CTR_{CE} | Current Transfer Ratio, Collector to Emitter | $I_F = \pm 10\text{mA}, V_{CE} = 10\text{V}$ | H11AA4M | 100 | | | % |
| | | | H11AA3M | 50 | | | |
| | | | H11AA1M | 20 | | | |
| | | | H11AA2M | 10 | | | |
| | Current Transfer Ratio, Symmetry | $I_F = \pm 10\text{mA}, V_{CE} = 10\text{V}$ (Figure 11) | All | .33 | | 3.0 | |
| $V_{CE(SAT)}$ | Saturation Voltage, Collector to Emitter | $I_F = \pm 10\text{mA}, I_{CE} = 0.5\text{mA}$ | All | | | .40 | V |

Isolation Characteristics

| Symbol | Characteristic | Test Conditions | Min. | Typ.* | Max. | Units |
|-----------|-------------------------------------|-------------------------------------|-----------|-------|------|----------|
| C_{I-O} | Package Capacitance Input/Output | $V_{I-O} = 0, f = 1\text{MHz}$ | | 0.7 | | pF |
| V_{ISO} | Isolation Voltage | $f = 60\text{Hz}, t = 1\text{sec.}$ | 7500 | | | Vac(pk) |
| R_{ISO} | Isolation Resistance | $V_{I-O} = 500\text{VDC}$ | 10^{11} | | | Ω |

*Typical values at $T_A = 25^\circ\text{C}$

Safety and Insulation Ratings

As per IEC 60747-5-2, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Symbol | Parameter | Min. | Typ. | Max. | Unit |
|-------------------|---|-----------------|-----------|------|-------------------|
| | Installation Classifications per DIN VDE 0110/1.89 Table 1 | | | | |
| | For Rated Main Voltage < 150Vrms | | I-IV | | |
| | For Rated Main voltage < 300Vrms | | I-IV | | |
| | Climatic Classification | | 55/100/21 | | |
| | Pollution Degree (DIN VDE 0110/1.89) | | 2 | | |
| CTI | Comparative Tracking Index | 175 | | | |
| V _{PR} | Input to Output Test Voltage, Method b, V _{IORM} × 1.875 = V _{PR} , 100% Production Test with t _m = 1 sec, Partial Discharge < 5pC | 1594 | | | V _{peak} |
| | Input to Output Test Voltage, Method a, V _{IORM} × 1.5 = V _{PR} , Type and Sample Test with t _m = 60 sec, Partial Discharge < 5pC | 1275 | | | V _{peak} |
| V _{IORM} | Max. Working Insulation Voltage | 850 | | | V _{peak} |
| V _{IOTM} | Highest Allowable Over Voltage | 6000 | | | V _{peak} |
| | External Creepage | 7 | | | mm |
| | External Clearance | 7 | | | mm |
| | Insulation Thickness | 0.5 | | | mm |
| RIO | Insulation Resistance at T _s , V _{IO} = 500V | 10 ⁹ | | | Ω |

Typical Performance Characteristics

Fig. 1 Input Voltage vs. Input Current

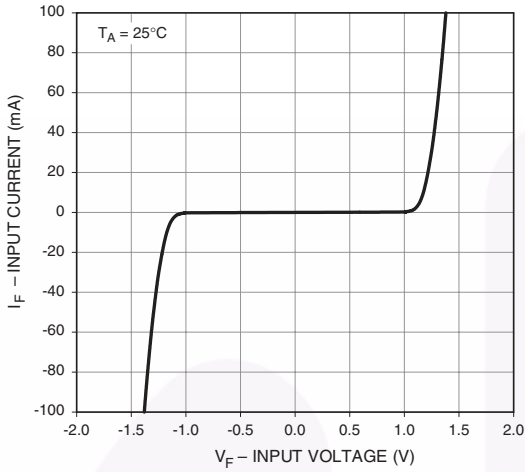


Fig. 2 Normalized CTR vs. Forward Current

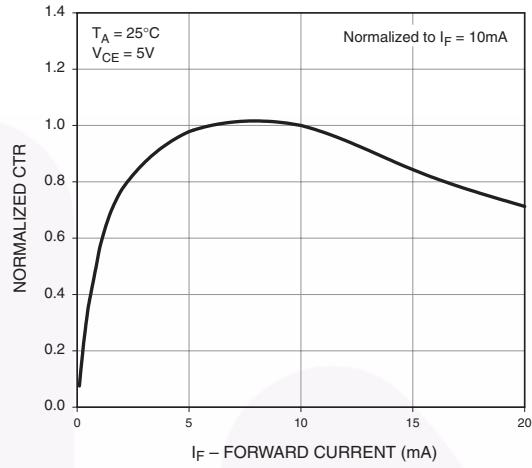


Fig. 3 Normalized CTR vs. Ambient Temperature

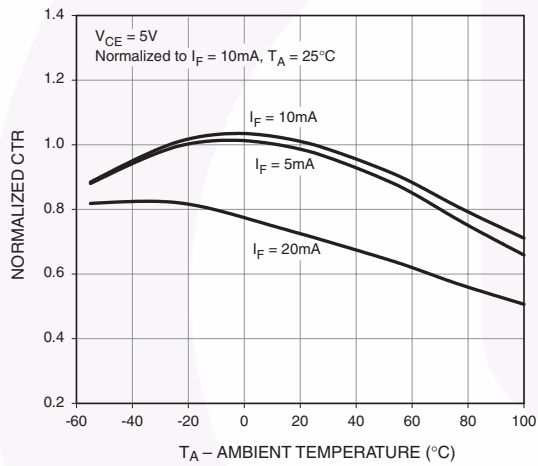


Fig. 4 CTR vs. RBE (Unsaturated)

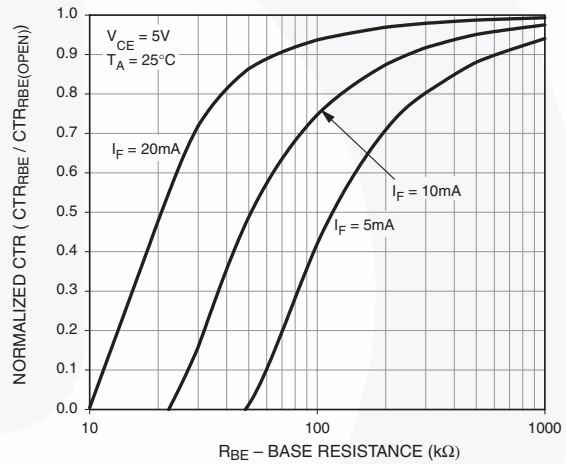


Fig. 5 CTR vs. RBE (Saturated)

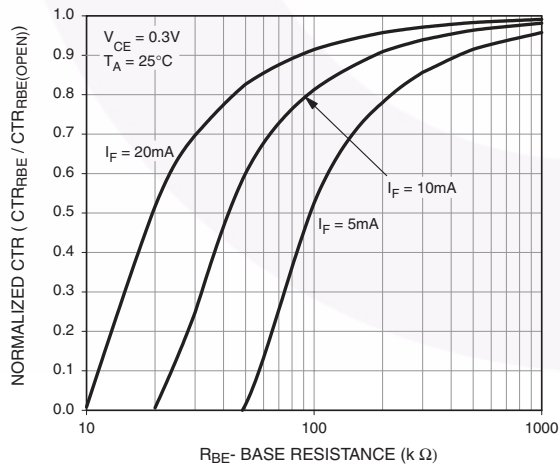
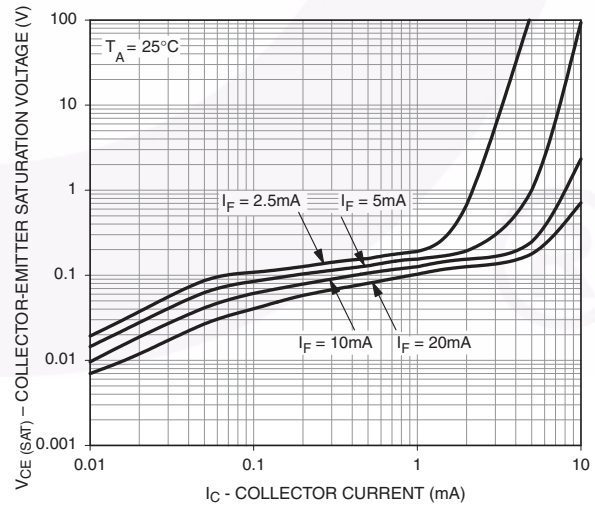


Fig. 6 Collector-Emitter Saturation Voltage vs. Collector Current



Typical Performance Characteristics (Continued)

Fig. 7 Switching Speed vs. Load Resistor

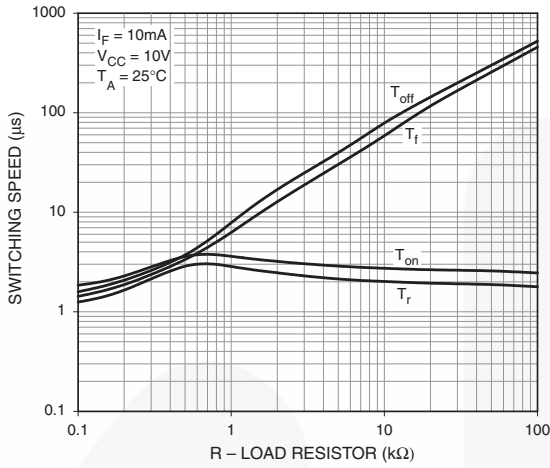


Fig. 8 Normalized t_{on} vs. R_{BE}

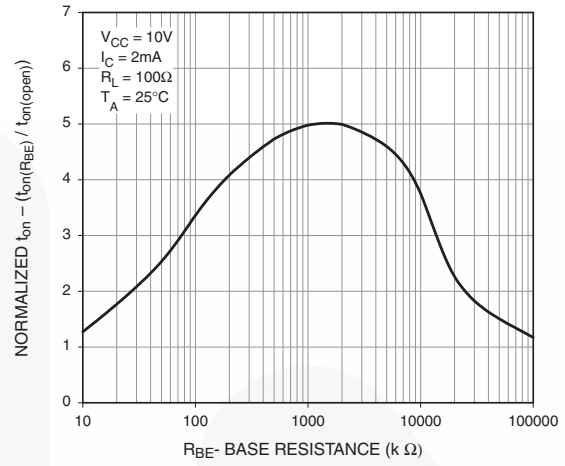


Fig. 9 Normalized t_{off} vs. R_{BE}

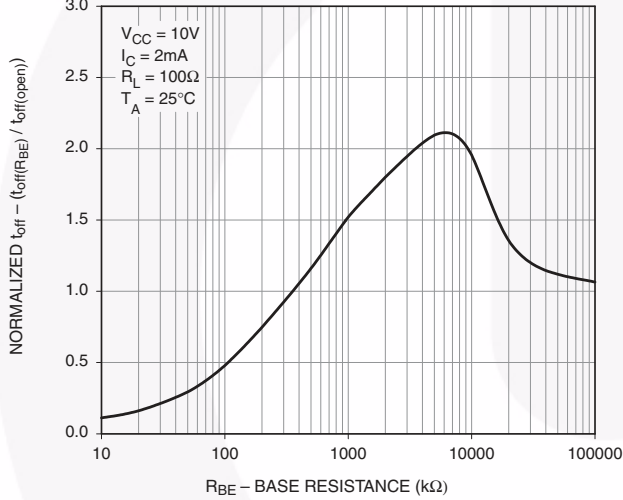


Fig. 10 Dark Current vs. Ambient Temperature

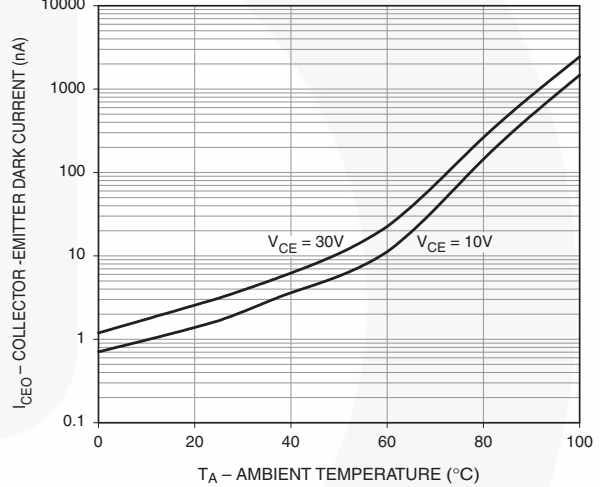
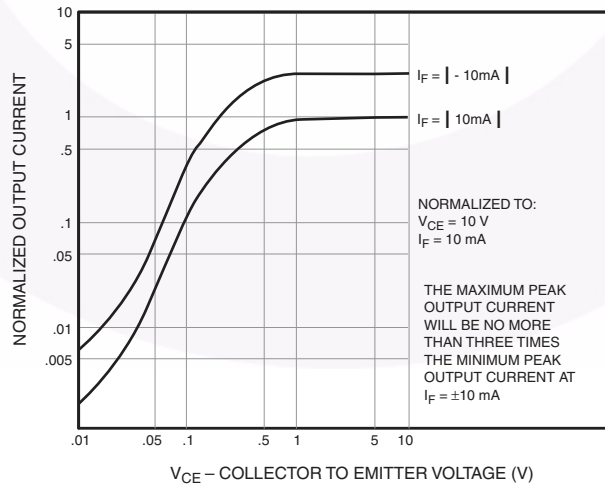
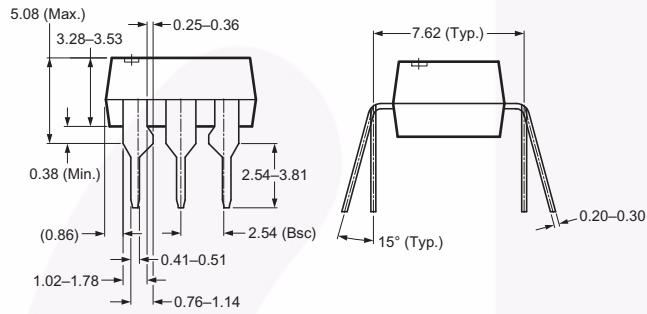
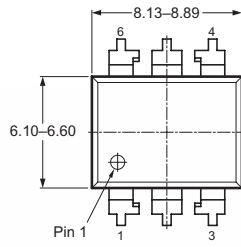


Fig. 11 Output Symmetry Characteristics

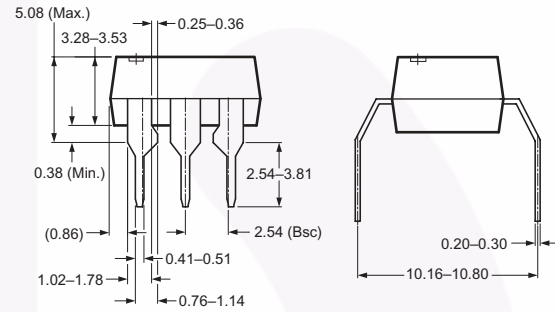
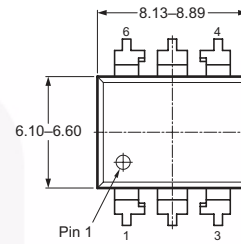


Package Dimensions

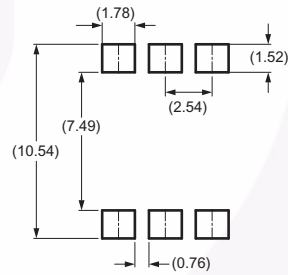
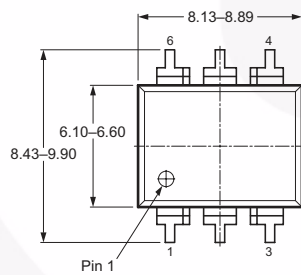
Through Hole



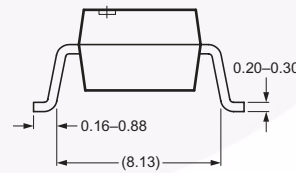
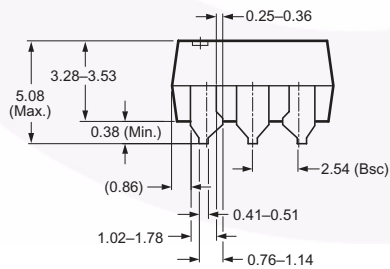
0.4" Lead Spacing



Surface Mount



Recommended Pad Layout

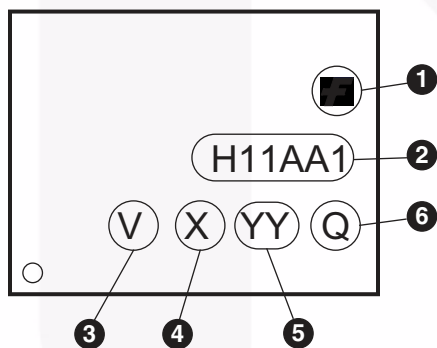


Note:
All dimensions in mm.

Ordering Information

| Option | Order Entry Identifier (Example) | Description |
|-----------|----------------------------------|--|
| No option | H11AA1M | Standard Through Hole Device |
| S | H11AA1SM | Surface Mount Lead Bend |
| SR2 | H11AA1SR2M | Surface Mount; Tape and Reel |
| T | H11AA1TM | 0.4" Lead Spacing |
| V | H11AA1VM | VDE 0884 |
| TV | H11AA1TVM | VDE 0884, 0.4" Lead Spacing |
| SV | H11AA1SVM | VDE 0884, Surface Mount |
| SR2V | H11AA1SR2VM | VDE 0884, Surface Mount, Tape and Reel |

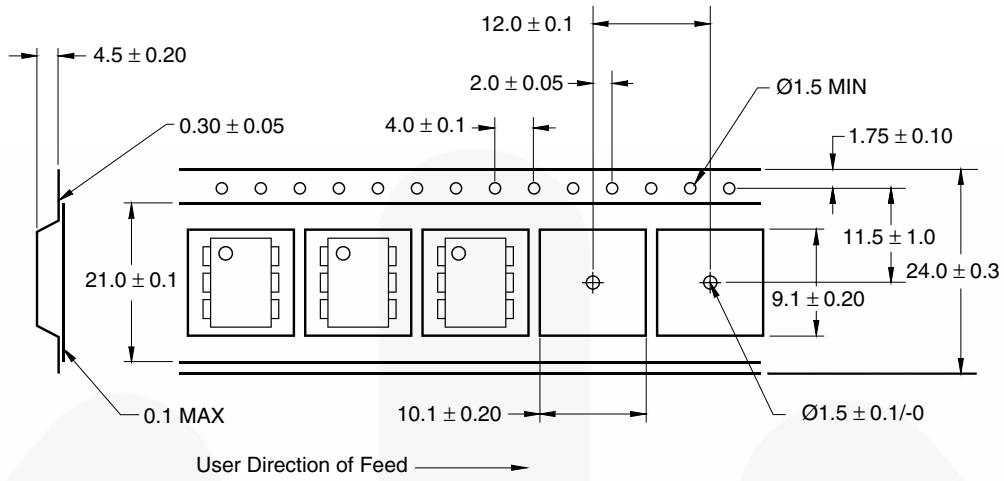
Marking Information



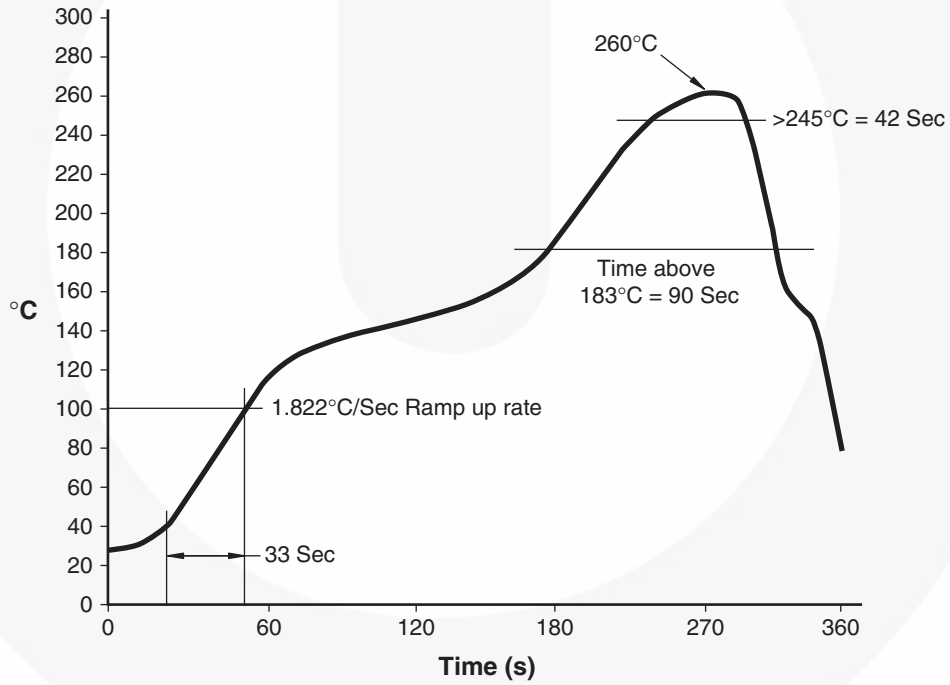
| Definitions | |
|-------------|--|
| 1 | Fairchild logo |
| 2 | Device number |
| 3 | VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table) |
| 4 | One digit year code, e.g., '3' |
| 5 | Two digit work week ranging from '01' to '53' |
| 6 | Assembly package code |

*Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.







Carrier Tape Specification



Reflow Profile





| | | | |
|--|---|---|---|
| Build it Now™ | FRFET™ | PowerXS™ | the power franchise |
| CorePLUS™ | Global Power Resource SM | Programmable Active Droop™ | TinyBoost™ |
| CorePOWER™ | Green FPS™ | QFET® | TinyBuck™ |
| CROSSVOLT™ | Green FPS™ e-Series™ | QS™ | TinyLogic® |
| CTL™ | Gmax™ | Quiet Series™ | TINYOPTO™ |
| Current Transfer Logic™ | GTO™ | RapidConfigure™ | TinyPower™ |
| EcoSPARK® | IntelliMAX™ |  ™ | TinyPWM™ |
| EfficientMax™ | ISOPLANAR™ | Saving our world, 1mW/W/kW at a time™ | TinyWire™ |
| EZSWITCH™* | MegaBuck™ | SmartMax™ | TriFault Detect™ |
|  ™* | MICROCOUPLER™ | SMART START™ | TRUECURRENT™* |
|  ® | MicroFET™ | SPM® | SerDes™ |
| Fairchild® | MillerDrive™ | STEALTH™ |  ™ |
| Fairchild Semiconductor® | MotionMax™ | SuperFET™ | UHC® |
| FACT Quiet Series™ | Motion-SPM™ | SuperSOT™-3 | Ultra FRFET™ |
| FACT® | OPTOLOGIC® | SuperSOT™-6 | UniFET™ |
| FAST® | OPTOPLANAR® | SuperSOT™-8 | VCX™ |
| FastvCore™ |  ® | SupreMOS™ | VisualMax™ |
| FETBench™ | PDP SPM™ | SyncFET™ | XS™ |
| FlashWriter®* | Power-SPM™ | Sync-Lock™ | |
| FPS™ | |  ™ | |

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms